

What is claimed is:

1. A stress-free lead frame (1) comprising;  
a lead frame (10) having a plurality of  
integrated circuits (11), each of said plurality of  
5 integrated circuits having a die pad (12) and a  
plurality of leads (13); and  
a peripheral pad (14) surrounding said lead frame  
(10),  
characterised by  
10 said peripheral pad (14) being provided with a  
plurality of stress-relief means (15).
2. A stress-free lead frame (1) comprising;  
a lead frame (10) having a plurality of  
integrated circuits (11), each of said plurality of  
15 integrated circuits having a die pad (12) and a  
plurality of leads (13); and  
a peripheral pad (14) surrounding said lead frame  
(10),  
characterised by  
20 said peripheral pad (14) being provided with a  
plurality of interlocking means (16).
3. A stress-free lead frame (1) as claimed in Claim  
1 further characterised by said plurality of stress-  
relief means (12) being holes and slots.
4. A stress-free lead frame (2) as claimed in Claim  
1 further characterised by said holes and slots being  
arranged in multiple rows.

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A2

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A2  
concluded

5. A stress-free lead frame (3) as claimed in Claim 2 further characterised by said interlocking means (16) being a plurality of slots.

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A3

6. A stress-free lead frame (1) as claimed in Claim 4 or Claim 5 further characterised by said holes and slots are arranged side by side at equal intervals.

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